110E

11DIR 🛮 2

11B 🛮 3

GND [] 4

10B 🛮 5

9B 🛮 6

V<sub>CC</sub>  $\sqrt{17}$ 

8BI [] 8

8BO 🛮 9

GND 1 10

7BO 🛮 11

6BI 🛮 12

6BO II 13

5BO 14

GND 15

4BO 🛮 16

4BI 🛮 17

V<sub>CC</sub> ☐ 18

3BO 🛮 19

2BI 🛮 20

GND 21 2BO 22

1BO 🛮 23

1BI 🛮 24

DGG OR DL PACKAGE

(TOP VIEW)

SCBS227J - JULY 1993 - REVISED AUGUST 2003

48∏ V<sub>CC</sub>BIAS

47 🛮 11A

46 10DIR

45 GND

44 **∏** 10A

43 | 9A

42 V<sub>CC</sub>

41 9DIR

39 | GND

40 8A

38 🛮 7A

37 7BI

36 A

35 🛮 5A

34 GND

33 5BI

32 AA

31 V<sub>CC</sub>

30 3A

29 3BI

27 2A

26 1A

25 OE

28 I GND

- Member of the Texas Instruments Widebus™ Family
- Supports the VME64 ETL Specification
- Reduced TTL-Compatible Input Threshold Range
- High-Drive Outputs (I<sub>OH</sub> = -60 mA, I<sub>OL</sub> = 90 mA) Support Equivalent 25-Ω Incident-Wave Switching
- V<sub>CC</sub>BIAS Pin Minimizes Signal Distortion During Live Insertion
- Internal Pullup Resistor on OE Keeps
   Outputs in High-Impedance State During
   Power Up or Power Down
- Distributed V<sub>CC</sub> and GND Pins Minimize High-Speed Switching Noise
- Equivalent 25-Ω Series Damping Resistor on B Port
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors

### description/ordering information

The SN74ABTE16246 is an 11-bit noninverting transceiver designed for asynchronous two-way communication between buses. This device has open-collector and 3-state outputs. The device

allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable  $(\overline{OE})$  input can be used to disable the device so that the buses are effectively isolated. When  $\overline{OE}$  is low, the device is active.

The B port has an equivalent  $25-\Omega$  series output resistor to reduce ringing. Active bus-hold inputs on the B port hold unused or floating inputs at a valid logic level.

The A port provides for the precharging of the outputs via  $V_{CC}BIAS$ , which establishes a voltage between 1.3 V and 1.7 V when  $V_{CC}$  is not connected.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

#### ORDERING INFORMATION

TA	PACK	\GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74ABTE16246DL	ABTE16246
	330P - DL	Tape and reel	SN74ABTE16246DLR	AB1E10240
	TSSOP – DGG	Tape and reel	SN74ABTE16246DGGR	ABTE16246

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

# **SN74ABTE16246** 11-BIT INCIDENT-WAVE SWITCHING BUS TRANSCEIVER WITH 3-STATE AND OPEN-COLLECTOR OUTPUTS SCBS227J – JULY 1993 – REVISED AUGUST 2003

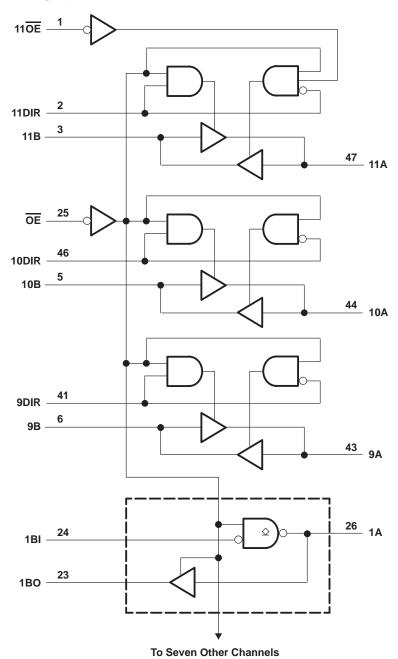
#### **FUNCTION TABLE**

		INPUTS			OPERATION
OE	9DIR	10DIR	11DIR	110E	OPERATION
Н	Х	Х	Х	Х	Isolation
L	Χ	Х	Х	Χ	1BI–8BI data to 1A–8A bus (OC <sup>†</sup> ), 1A–8A data to 1BO–8BO bus
L	L	Х	Х	Х	9A data to 9B bus
L	Н	X	X	X	9B data to 9A bus
L	X	L	Χ	X	10A data to 10B bus
L	X	Н	Χ	X	10B data to 10A bus
L	X	X	L	L	11A data to 11B bus
L	X	X	L	Н	11A, 11B isolation
L	Χ	X	Н	Χ	11B data to 11A bus

<sup>†</sup>OC = Open-collector outputs



## logic diagram (positive logic)





SCBS227J - JULY 1993 - REVISED AUGUST 2003

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> and V <sub>CC</sub> BIAS	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	70°C/W
DL package	63°C/W
Storage temperature range, T <sub>sta</sub>	65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V <sub>CC</sub> , V <sub>CC</sub> BIAS	Supply voltage	4.5	5	5.5	V	
V	High-level input voltage	2			V	
VIH	High-level input voltage	Except OE	1.6			V
\/	l aux lavel input veltage				0.8	V
VIL	Low-level input voltage			1.4		
Vон	High-level output voltage	1A-8A	0		5.5	V
٧ <sub>I</sub>	Input voltage	-	0		Vcc	V
la	B bus				-12	mA
ЮН	High-level output current			-64	mA	
la.	Low lovel output oursent	B bus			12	mA
IOL	Low-level output current	A bus			90	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled			10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# **SN74ABTE16246** 11-BIT INCIDENT-WAVE SWITCHING BUS TRANSCEIVER WITH 3-STATE AND OPEN-COLLECTOR OUTPUTS SCBS227J – JULY 1993 – REVISED AUGUST 2003

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CC	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2	V
		V <sub>CC</sub> = 5.5 V,	I <sub>OH</sub> = -100 μA			V <sub>CC</sub> -0.2	
	B port	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -1 mA	2.4			
\/		VCC = 4.5 V	I <sub>OH</sub> = -12 mA	2			V
VOH		V <sub>CC</sub> = 5.5 V,	I <sub>OH</sub> = -1 mA			4.5	V
	9A-11A	V <sub>CC</sub> = 4.5 V	$I_{OH} = -32 \text{ mA}$	2.4			
		VCC = 4.5 V	$I_{OH} = -64 \text{ mA}$	2			
IOH	1A-8A	$V_{CC} = 4.5 \text{ V},$	V <sub>OH</sub> = 5.5 V			20	μΑ
	B port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 1 mA			0.4	
\/01	Броп	VCC = 4.5 V	$I_{OL} = 12 \text{ mA}$			0.8	V
VOL	A port	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA			0.55	v
		VCC = 4.5 V	I <sub>OL</sub> = 90 mA				
V <sub>hys</sub>					100		mV
		V 45V	V <sub>I</sub> = 0.8 V	100			
I <sub>I</sub> (hold)	B port	V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 2 V	-100			μΑ
		V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0 to 5.5 V			±500	
1.	Control inputs	V <sub>CC</sub> = 5.5 V	V. Vaaar CND			±1	
l <sub>l</sub>	A or B ports	$V_{CC} = 5.5 \text{ V}, \overline{OE} = V_{CC}$	$V_I = V_{CC}$ or GND			±20	μΑ
lozh <sup>‡</sup>	9A-11A	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.7 V			10	μΑ
loz <sub>L</sub> ‡	9A-11A	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 0.5 V			-10	μΑ
lo.	A port	V00 - 55 V	Vo - 25 V	-50		-180	mA
Ю	B port	$V_{CC} = 5.5 \text{ V}, \qquad V_{O} = 2.5 \text{ V}$		-25		-90	IIIA
l <sub>off</sub>		$V_{CC} = 0$ , $V_I$ or $V_O \le 4.5$ V,	V <sub>CC</sub> BIAS = 0			±100	μΑ
			Outputs high		28	36	
ICC	A or B ports	$V_{CC} = 5.5 \text{ V}, I_{O} = 0,$ $V_{I} = V_{CC} \text{ or GND}$	Outputs low		38	48	mA
		17 166 3. 3.12	Outputs disabled		20	32	
ICCD	A or B ports	V <sub>CC</sub> = 5 V, C <sub>I</sub> = 50 pF	OE high		0.02		mA/
ICCD	A of D ports	VCC = 3 V, OL = 30 рг	OE low		0.33		MHz
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			2.5	4	pF
C <sub>io</sub>	I/O ports	$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			4.5	8	pF

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ The parameters I<sub>OZH</sub> and I<sub>OZL</sub> include the input leakage current.

SCBS227J - JULY 1993 - REVISED AUGUST 2003

## live-insertion specifications over recommended operating free-air temperature range

PA	RAMETER		MIN	TYP <sup>†</sup>	MAX	UNIT		
I <sub>CC</sub> (V <sub>CC</sub> BIAS)		$V_{CC} = 0 \text{ to } 4.5 \text{ V},$	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V,$	IO(DC) = 0		250	700	μA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}^{\ddagger},$	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V,$	IO(DC) = 0			20	μΑ
\/-	) / A ====t	V0	$V_{CC}BIAS = 4.5 V \text{ to } 5.5 V$	1.1	1.5	1.9	V	
Vo	A port	VCC = 0	V <sub>CC</sub> BIAS = 4.75 V to 5.25 V		1.3	1.5	1.7	· ·
lo.	IO A port VCC =	Vaa - 0	V00PIAS - 4 5 V	V <sub>O</sub> = 0	-20		-100	
L 10		vCC = 0,	V <sub>CC</sub> BIAS = 4.5 V	V <sub>O</sub> = 3 V	20		100	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V A = 25°C	', ;	MIN	MAX	UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX			
tPLH	А	В	1.5	3.1	4.2	1.5	5.2	ns
<sup>t</sup> PHL	٨	В	1.5	3.5	4.6	1.5	5.2	113
tPLH	9B–11B	9A–11A	1.5	3	3.8	1.5	4.5	ns
<sup>t</sup> PHL	9D-11D	9A-11A	1.5	3.2	4	1.5	4.5	115
t <sub>PLH</sub> §			1.5	3.2	4	1.5	4.5	
t <sub>PLH</sub> ¶	1B–8B	1A-8A	7.5	8.9	9.7	7.5	10.3	ns
t <sub>PHL</sub>			1.5	3.2	4	1.5	4.5	
<sup>t</sup> PZH	ŌĒ	9A-11A	2	4.3	5.3	2	6.2	ns
tPZL	OE	1A-11A	2	4.4	5.4	2	6.8	115
<sup>t</sup> PZH	ŌĒ	В	2	4.3	6	2	7.1	ns
tPZL	OE	В	2	4.5	6.4	2	7.3	115
<sup>t</sup> PHZ	ŌĒ	9A-11A	2	4.2	5.9	2	6.7	ns
<sup>t</sup> PLZ	OE	1A-11A	2	3.5	4.6	2	5.1	115
<sup>t</sup> PHZ	ŌĒ	В	2.5	4.3	6.2	2.5	7	ns
tPLZ	ĢL		2	3.6	5	2	5.5	115

Measurement point is VOL + 0.3 V.



<sup>‡</sup> VCC - 0.5 V < VCCBIAS

<sup>¶</sup> Measurement point is V<sub>OL</sub> + 1.5 V.

SCBS227J – JULY 1993 – REVISED AUGUST 2003

# extended switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT) LOAD		V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN	MAX	UNIT
	(1141-01)	(0011 01)		MIN	TYP	MAX			
<sup>t</sup> PLH	9B–11B	9A-11A	Rχ = 13 Ω	1.5	3.2	4	1.5	4.8	ns
t <sub>PHL</sub>	96-116	9A-11A	KX = 13 22	1.5	3.8	4.7	1.5	5.6	115
tPHL	1B-8B	1A-8A	Rχ = 13 Ω	1.5	3.3	4.2	1.5	4.8	ns
t <sub>PLH</sub>	0D 44D	9A-11A	Dv. 26.0	1.5	3.1	4	1.5	4.6	
tPHL	9B–11B	9A-11A	$R\chi = 26 \Omega$	1.5	3.5	4.4	1.5	4.9	ns
t <sub>PHL</sub>	1B–8B	1A-8A	Rχ = 26 Ω	1.5	3.1	4	1.5	4.4	ns
tPLH	0D 44D	4.4.0.4	Rχ = 56 Ω	1.5	3	3.8	1.5	4.5	—l ns l
t <sub>PHL</sub>	9B–11B	1A–8A	KX = 20.75	1.5	3.3	4.2	1.5	4.7	
tPHL	1B–8B	1A-8A	Rχ = 56 Ω	1.5	3	4	1.5	4.4	ns
	В	А	R <sub>X</sub> = Open		0.1	0.6		2	
t <sub>sk(p)</sub>	А	В	R <sub>X</sub> = Open		0.4	0.8		2	ns
,	В	А	Rχ = 26 Ω		0.3	0.8		2	
	В	А	R <sub>X</sub> = Open		0.3	0.7		1.3	
t <sub>sk(o)</sub>	А	B R <sub>X</sub> = Open			0.7	1.1		1.3	ns
	В	А	Rχ = 26 Ω		0.5	1		1.3	
t <sub>t</sub> †	В	Α	Rχ = 26 Ω	0.5	0.8	1.5	0.5	1.5	ns
t <sub>t</sub> ‡	А	В	R <sub>X</sub> = Open	3.5	5.5	7.3	3.5	7.9	ns

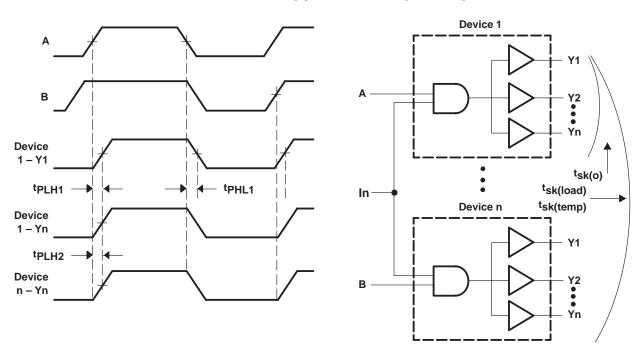
# extended output characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	LOAD	MIN MA	X UNIT
4	А	В	V <sub>CC</sub> = constant,		2	.5
<sup>t</sup> sk(temp)	В	Α	$\Delta T_A = 20^{\circ}C$	$R_X = 56 \Omega$		4 ns
<sup>t</sup> sk(load)	В	А	V <sub>CC</sub> = constant, Temperature = constant	$R_X = 13, 26, \text{ or } 56 \Omega$		4 ns

 $<sup>^\</sup>dagger$   $t_t$  is measured between 1 V and 2 V of the output waveform.  $^\ddagger$   $t_t$  is measured between 10% and 90% of the output waveform.

SCBS227J - JULY 1993 - REVISED AUGUST 2003

#### PARAMETER MEASUREMENT INFORMATION



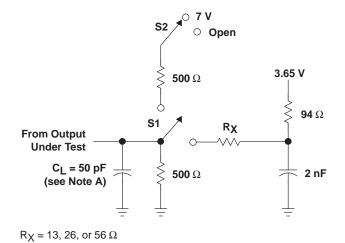
- NOTES: A. Pulse skew,  $t_{sk(p)}$ , is defined as the difference in propagation-delay times  $t_{PLH1}$  and  $t_{PHL1}$  on the same terminal at identical operating conditions.
  - B. Output skew,  $t_{sk(0)}$ , is defined as the difference in propagation delay of any two outputs of the same device switching in the same direction (e.g.,  $|t_{PLH1} t_{PLH2}|$ ).
  - C. Temperature skew,  $t_{sk(temp)}$ , is the output skew of two devices, both having the same value of  $V_{CC} \pm 1\%$  and with package temperature differences of 20°C.
  - D. Load skew,  $t_{sk(load)}$ , is measured with  $R_X$  in Figure 2 at 13  $\Omega$  for one unit and 56  $\Omega$  for the other unit.

Figure 1. Voltage Waveforms for Extended Characteristics



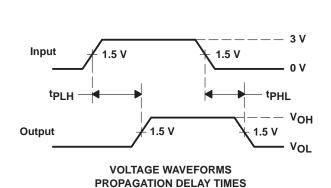
SCBS227J - JULY 1993 - REVISED AUGUST 2003

#### PARAMETER MEASUREMENT INFORMATION

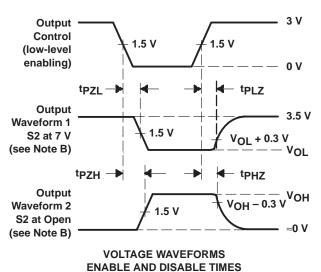


SWITCHING TABLE LOADS	S1	S2
tPLH/tPHL (9A-11A and B port)	Up	Open
tPLH/tPHL (1A-8A)	Up	7 V
tPLZ/tPZL	Up	7 V
t <sub>PHZ</sub> /t <sub>PZH</sub> (except 1A-8A)	Up	Open

EXTENDED SWITCHING TABLE LOADS	S1	S2
tPLH/tPHL/t <sub>Sk</sub> (A port)	Down	Х
tpLH/tpHL/t <sub>Sk</sub> (B port)	Up	Open
t <sub>t</sub> (A port) (see Note E)	Down	Х
t <sub>t</sub> (B port) (see Note F)	Up	Open



LOAD CIRCUIT



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq 2.5~ns$ ,  $t_f \leq 2.5~ns$ .
- D. The outputs are measured one at a time with one transition per measurement.
- E. t<sub>t</sub> is measured between 1 V and 2 V of the output waveform.
- F. t<sub>t</sub> is measured between 10% and 90% of the output waveform.

Figure 2. Load Circuit and Voltage Waveforms

www.ti.com 13-Jul-2022

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74ABTE16246DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples
SN74ABTE16246DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples
SN74ABTE16246DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTE16246	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



# **PACKAGE OPTION ADDENDUM**

www.ti.com 13-Jul-2022

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022

## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTE16246DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022



### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTE16246DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABTE16246DLR	SSOP	DL	48	1000	367.0	367.0	55.0

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022

## **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABTE16246DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

# DL (R-PDSO-G48)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.





SMALL OUTLINE PACKAGE



### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
  4. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated